PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Satoshi FUJISAWA	02/01/2011
Yuji SUZUKI	02/01/2011
Takeo UNO	02/03/2011
Koichi HATTORI	02/15/2011
Naoya KUWASAKI	02/07/2011

RECEIVING PARTY DATA

Name:	Furukawa Electric Co., Ltd.
Street Address:	2-3, Marunouchi 2-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	100-8322

Name:	Nippon Steel Chemical Co., Ltd.
Street Address:	14-1, Sotokanda 4-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	101-0021

OP $40.00 13055375

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13055375

CORRESPONDENCE DATA

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Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
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Email: asomaiel@oblon.com
Correspondent Name: Oblon, Spivak, et al.

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ATTORNEY DOCKET NUMBER:	374865US8XPCT
NAME OF SUBMITTER:	Adel Samuel

Total Attachments: 4
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P02636US
078012US

Docket Number: ______________

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

Flexible Copper Clad Laminate

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Furukawa Electric Co., Ltd., 2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8322 Japan and Nippon Steel Chemical Co., Ltd., 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-0021 Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, is order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 13/055,375
Filing Date: April 21, 2011.

This assignment executed on the dates indicated below.

Satoshi FUJISAWA
Name of first or sole inventor — Execution date of U.S. Patent Application

Tokyo, Japan
Residence of first or sole inventor

FUJISAWA Satoshi — 2/01/2011
Signature of first or sole inventor — Date of this assignment

Yuji SUZUKI

Name of second inventor — Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Yuji Suzuki — 01/02/2011

Signature of second inventor — Date of this assignment

Takeo UNO

Name of third inventor — Execution date of U.S. Patent Application

Tokyo, Japan

Residence of third inventor

Takeo Uno — Feb 3, 2011

Signature of third inventor — Date of this assignment

Koichi HATTORI

Name of fourth inventor — Execution date of U.S. Patent Application

Chiba, Japan

Residence of fourth inventor

Signature of fourth inventor — Date of this assignment

Naoya KUWASAKI

Name of fifth inventor — Execution date of U.S. Patent Application

Fukuoka, Japan

Residence of fifth inventor

Signature of fifth inventor — Date of this assignment

G20090030
098012US

Docket Number: _______________

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

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for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Furukawa Electric Co., Ltd., 2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8322 Japan and Nippon Steel Chemical Co., Ltd., 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-0021 Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, is order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 13/055,375
Filing Date: April 21, 2011.

This assignment executed on the dates indicated below.

Satoshi FUJISAWA
Name of first or sole inventor — Execution date of U.S. Patent Application

Tokyo, Japan
Residence of first or sole inventor

____
Signature of first or sole inventor — Date of this assignment

Yuji SUZUKI

Name of second inventor   Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Signature of second inventor   Date of this assignment

Takeo UNO

Name of third inventor   Execution date of U.S. Patent Application

Tokyo, Japan

Residence of third inventor

Signature of third inventor   Date of this assignment

Koichi HATTORI

Name of fourth inventor   Execution date of U.S. Patent Application

Chiba, Japan

Residence of fourth inventor

Koichi Hattori   February 15, 2011

Signature of fourth inventor   Date of this assignment

Naoya KUWASAKI

Name of fifth inventor   Execution date of U.S. Patent Application

Fukuoka, Japan

Residence of fifth inventor

Naoya Kuwasaki   February 7, 2011.

Signature of fifth inventor   Date of this assignment